

Title (en)

BACKPLANE FOOTPRINT FOR HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTORS

Title (de)

RÜCKPLATTEN-FUSSABDRUCK FÜR ELEKTRISCHE STECKVERBINDER MIT HOHER GESCHWINDIGKEIT UND HOHER DICHTHE

Title (fr)

EMPREINTE DE FACE ARRIÈRE DESTINÉE À DES CONNECTEURS ÉLECTRIQUES À HAUTE DENSITÉ ET HAUTE VITESSE

Publication

**EP 3707971 A4 20210728 (EN)**

Application

**EP 18875264 A 20181108**

Priority

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- US 2018059757 W 20181108

Abstract (en)

[origin: WO2019094549A1] A printed circuit board includes a plurality of layers including conductive layers separated by dielectric layers, the conductive layers including a signal layer; and via patterns formed in the plurality of layers, each of the via patterns comprising first and second signal vias extending from a first surface of the printed circuit board to the signal layer, the signal layer including first and second signal traces connected to the first and second signal vias, respectively, the signal layer further including a ground conductor located between the signal traces and adjacent signal-carrying elements.

IPC 8 full level

**H05K 1/02** (2006.01)

CPC (source: EP)

**H05K 1/0219** (2013.01); **H05K 1/0225** (2013.01); **H05K 1/0245** (2013.01); **H05K 1/0251** (2013.01); **H05K 1/0298** (2013.01); **H05K 2201/09409** (2013.01)

Citation (search report)

- [X1] US 2005247482 A1 20051110 - NAKAMURA NAOKI [JP]
- [X1] EP 3200572 A1 20170802 - FUJIKURA LTD [JP], et al
- See also references of WO 2019094549A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

**WO 2019094549 A1 20190516**; CN 111602472 A 20200828; CN 111602472 B 20240206; EP 3707971 A1 20200916; EP 3707971 A4 20210728

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**US 2018059757 W 20181108**; CN 201880085756 A 20181108; EP 18875264 A 20181108